Design For AI & AI For Design – EDA Perspective and Practice

By Brian Li

Abstract:

The AI era has already arrived. Although current AI, based on large language models (LLMs), is still in the early stages of the overall AI revolution, it is already being widely applied across many industrial sectors. The demand for AI chips is extremely high. Efficient AI chip design and the use of AI to improve chip design productivity are two important areas. Various innovative solutions and technologies have already emerged in both areas. This presentation will explore some ideas and practices from the perspective of Electronic Design Automation (EDA).

Biography：

Brian Li is the Product Validation Group Director in the Digital and Signoff Group at Cadence Design Systems. He has been working in leading EDA companies, including Synopsys and Cadence, for over 20 years. During this time, he has been responsible for the validation, release, promotion, and key technology innovation of Cadence's digital implementation and signoff products.

Currently, Brian is a core member of the Cadence 3DIC team and the global leader of the Automotive Electronics R&D task force, focusing on 3DIC solution innovation and functional safety implementation and signoff innovation. He holds several key patents in the domains of functional safety implementation and hierarchical design methodology.

Brian graduated with a Master's degree in Computer Engineering from the East China Institute of Computation Technology in 2004 and from Shanghai JiaoTong University in 2001.